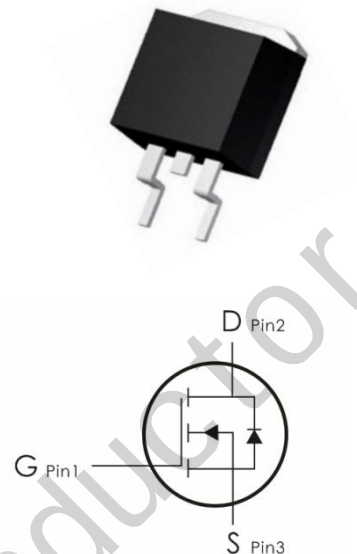


Features:

- ☐ Low Intrinsic Capacitances.
- ☐ Excellent Switching Characteristics.
- ☐ Extended Safe Operating Area.
- ☐ Unrivalled Gate Charge : $Q_g=60\text{nC}$ (Typ.).
- ☐ $BVDSS=100\text{V}$, $I_D=100\text{A}$
- ☐ $R_{DS(on)} : 0.012\Omega$ (Max) @ $V_G=10\text{V}$
- ☐ 100% Avalanche Tested



Absolute Maximum Ratings ($T_A=25^\circ\text{C}$ unless otherwise noted)

Symbol	Parameter	Maximum	Unit
V_{DSS}	Drain-to-Source Voltage	100	V
V_{GSS}	Gate-to-Source Voltage	± 25	V
I_D^3	Continuous Drain Current	$T_C=25^\circ\text{C}$	100
		$T_C=100^\circ\text{C}$	51
I_{DP}^4	Pulsed Drain Current	$T_C=25^\circ\text{C}$	219
I_{AS}^5	Avalanche Current	30	A
EAS^5	Avalanche energy	225	mJ
PD	Maximum Power Dissipation	$T_C=25^\circ\text{C}$	166
		$T_C=100^\circ\text{C}$	83
T_J, T_{STG}	Junction & Storage Temperature Range	-55~175	$^\circ\text{C}$

Thermal Characteristics

Symbol	Parameter	Typical	Unit
$R_{\theta jc}$	Thermal Resistance-Junction to Case	0.9	$^\circ\text{C/W}$
$R_{\theta ja}$	Thermal Resistance-Junction to Ambient	62.5	

Electrical Characteristics (T_A=25°C unless otherwise noted)

Symbol	Parameter	Test Conditions	Min.	Typ	Max.	Unit
Static Characteristics						
BV _{DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V, I _D =250uA	100	—	—	V
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} =80V, V _{GS} =0V	—	—	1	uA
		T _J =125°C	—	—	20	
V _{GS(th)}	Gate Threshold Voltage	V _{DS} =V _{GS} , I _D =250uA	2	3	4	V
I _{GSS}	Gate Leakage Current	V _{GS} =±25V, V _{DS} =0V	—	—	±100	nA
R _{DS(on)} ¹	Drain-Source On-Resistance	V _{GS} =10V, I _D =50A	—	10	12	mΩ
			—	—	—	
Diode Characteristics						
V _{SD} ¹	Diode Forward Voltage	I _{SD} =50A, V _{GS} =0V	—	—	1.3	V
I _S ³	Diode Continuous Forward Current		—	—	100	A
t _{rr}	Reverse Recovery Time	I _F =50A,	—	46	—	nS
Q _{rr}	Reverse Recovery Charge	dI/dt=100A/us	—	86	—	nC
Dynamic Characteristics ²						
R _G	Gate Resistance	V _{GS} =0V, V _{DS} =0V, Frequency=1MHz	—	1.2	—	Ω
C _{iss}	Input Capacitance	V _{GS} =0V, V _{DS} =25V Frequency=1MHz	—	2946	—	pF
C _{oss}	Output Capacitance		—	339	—	
C _{rss}	Reverse Transfer Capacitance		—	179	—	
t _{d(on)}	Turn-On Delay Time	V _{DD} =50V, I _D =30A, V _{GS} =10V, R _G =6.8Ω	—	15	—	nS
t _r	Rise Time		—	108	—	
t _{d(off)}	Turn-Off Delay Time		—	51	—	
t _f	Fall Time		—	59	—	
Gate Charge Characteristics ²						
Q _g	Total Gate Charge	V _{DS} =50V, V _{GS} =10V I _D =30A	—	60	—	nC
Q _{gs}	Gate-to-Source Charge		—	13.7	—	
Q _{gd}	Gate-to-Drain Charge		—	22.8	—	

Note: 1: Pulse test; pulse width ≤ 300μs, duty cycle ≤ 2%.

2: Guaranteed by design, not subject to production testing.

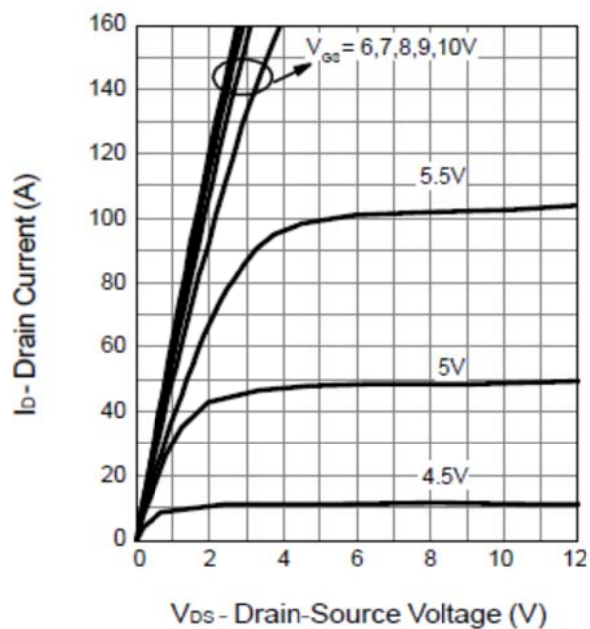
3: Package limitation current is 55A.

4: Repetitive rating, pulse width limited by max junction temperature.

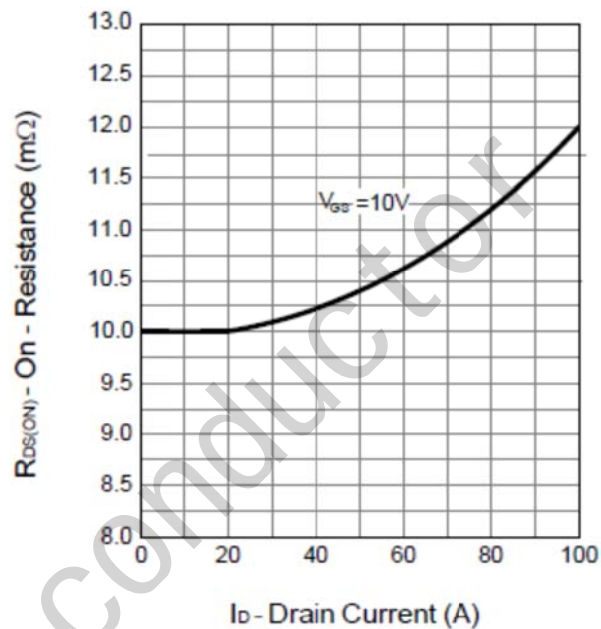
5: Starting T_J = 25°C, L = 0.5mH, I_{AS} = 30A.

Typical Characteristics

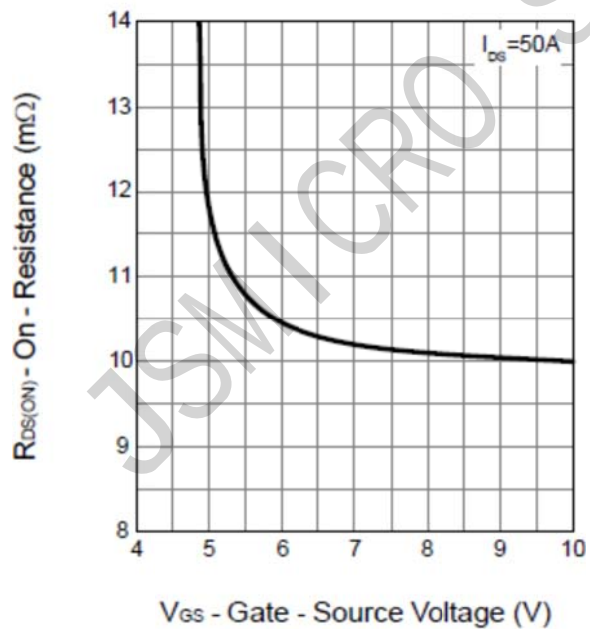
Output Characteristics



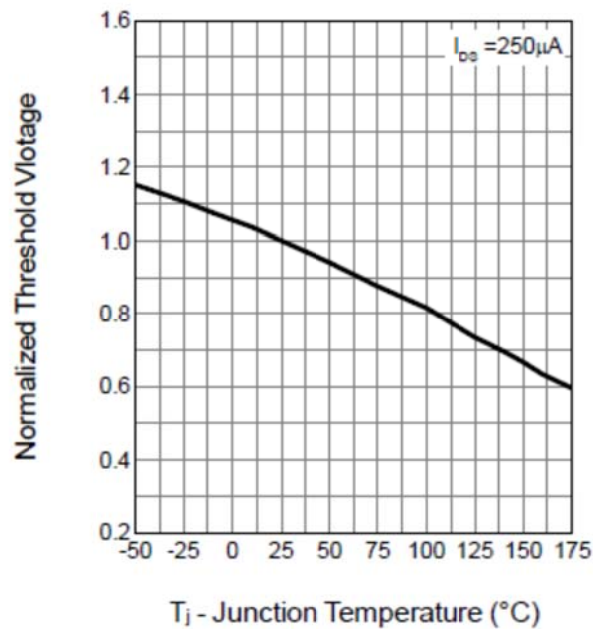
Drain-Source On Resistance



Drain-Source On Resistance

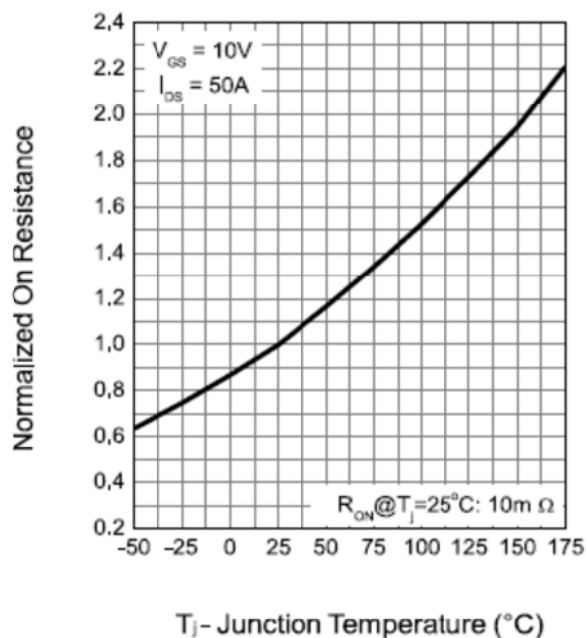


Gate Threshold Voltage

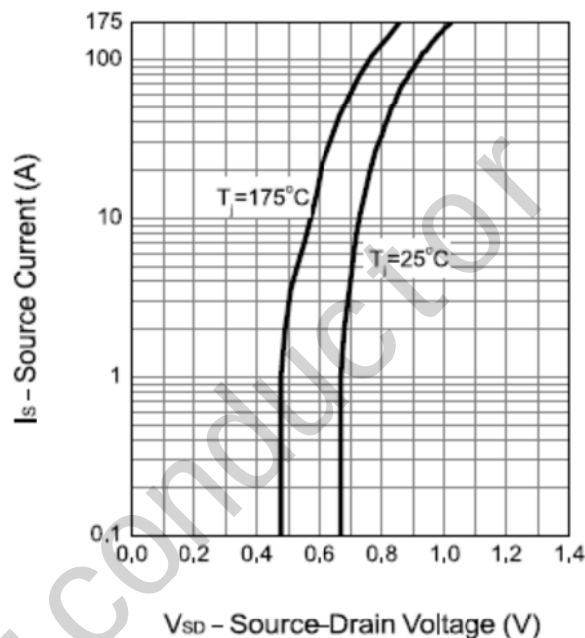


Typical Characteristics (Continued)

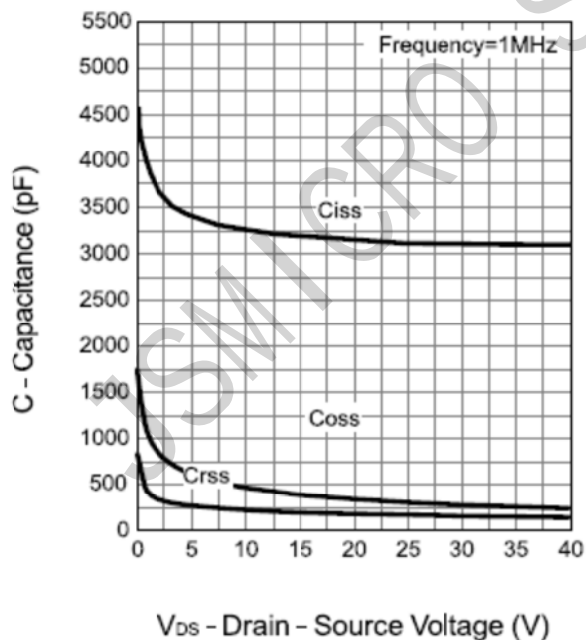
Drain-Source On Resistance



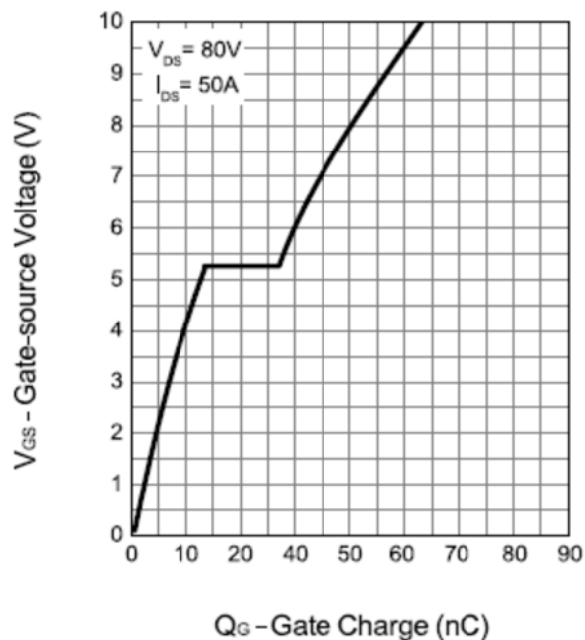
Source-Drain Diode Forward



Capacitance

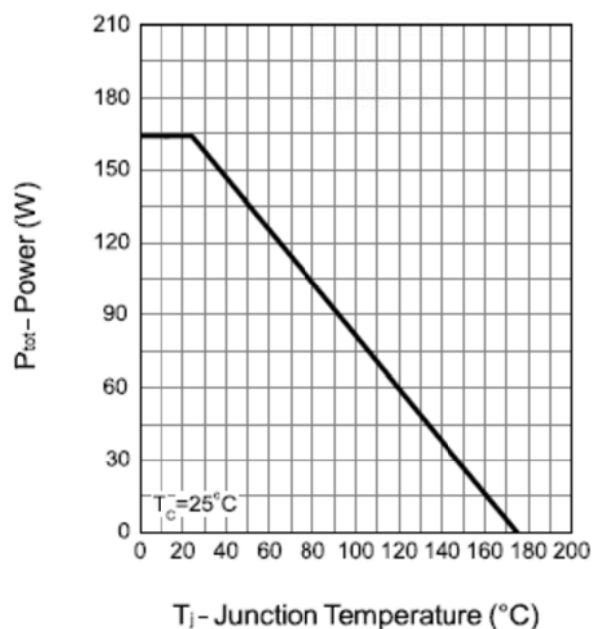


Gate Charge

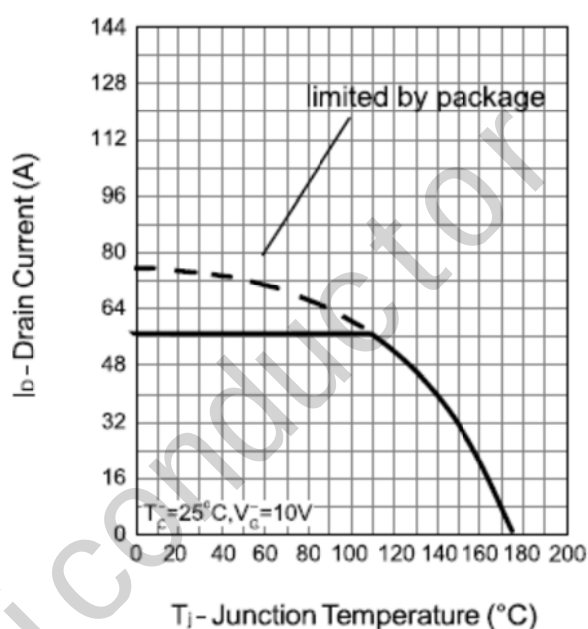


Typical Characteristics (Continued)

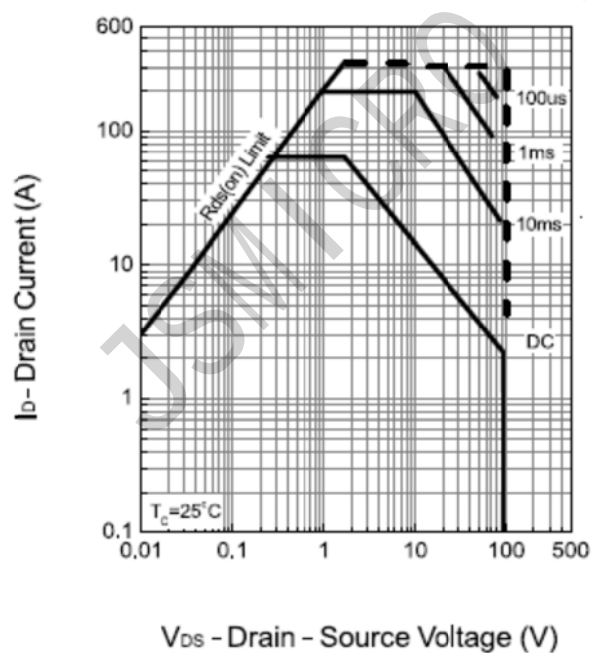
Power Dissipation



Drain Current



Safe Operation Area



Thermal Transient Impedance

